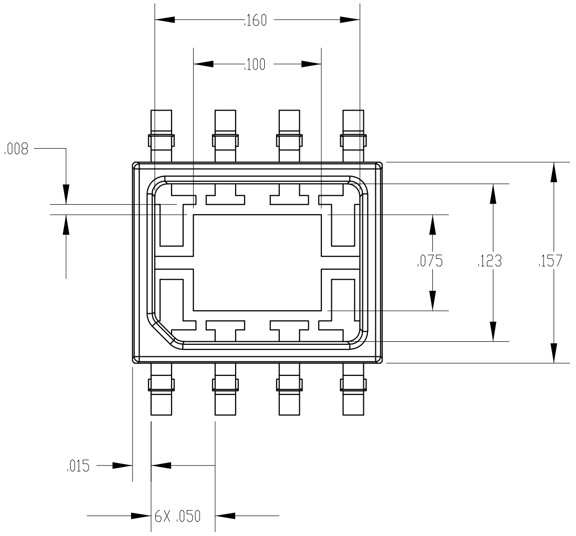
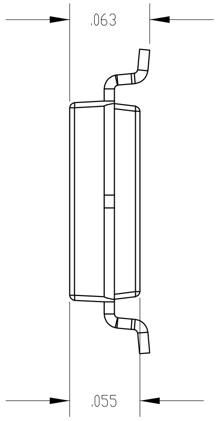
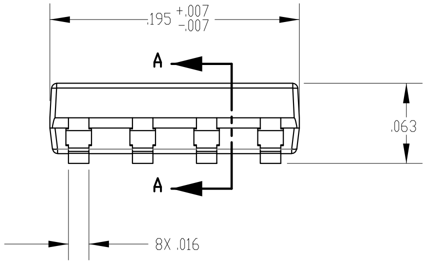
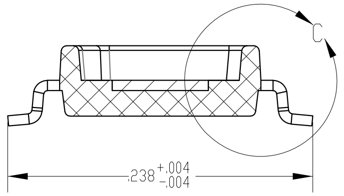
SSM P/N PSO081504

REVISIONS				
ZONE	REV.	DESCRIPTION	DATE	APPROVED
	A	ORIGINAL RELEASE	7/16/12	SS

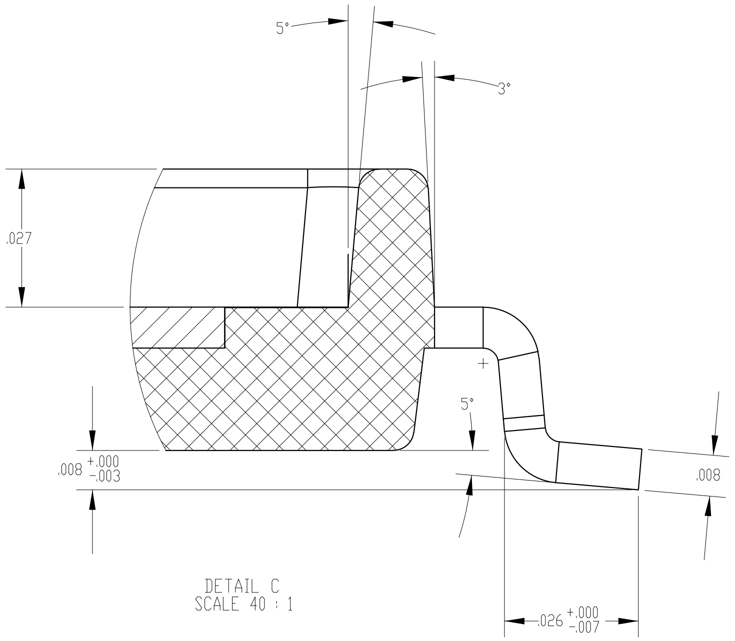




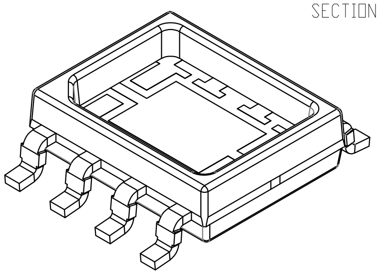




SECTION A-A



DETAIL C
SCALE 40 : 1



3. PACKAGE CONFORMS TO JEDEC MS-012.

2. FINISH: LEAD FRAME ELECTROLESS NICKEL PER MIL-C-26075, CLASS 1, 100 TO 300 MICROINCHES (2.5um - 7.6um) THICK. GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1.

1. MATERIALS: LEAD FRAME, COPPER ALLOY 194 FULL HARD. BODY: SEMICONDUCTOR GRADE MOLDING EPOXY.

GENERAL NOTES: (UNLESS OTHERWISE SPECIFIED)

	NAME	DATE
DRAWN	S. Swen	7/5/12
CHECKED	S. Swen	7/6/12
ENG APPR.	S. Swen	7/12/12

UNLESS OTHERWISE SPECIFIED:
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
FRACTIONAL: ± 1/16"
ANGULAR: ±0.5 degree
.X = ±.030 .XX±.010
.XXX = ±.005 .XXXX = ±.0005

MATERIAL SEE NOTE 1.
FINISH SEE NOTE 2.
DO NOT SCALE DRAWING

NEXT ASSY | USED ON
APPLICATION

COMMENTS:

TITLE:
SOIC, 8 LD, .150 WIDE PACKAGE OUTLINE DRAWING

SIZE B
DWG. NO. 500520
REV A
SCALE: 10:1
WEIGHT:
SHEET 1 OF 1

SPECTRUM
SEMICONDUCTOR MATERIALS, INC.

www.spectrum-semi.com Ph: (408) 435-5555 Fax: (408) 435-8226